

A Novel Multi-Context Non-Volatile Content-Addressable Memory Cell and Multi-Level Architecture for High Reliability and Density

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Outline

1 Introduction

2 Proposed MCC for High Reliability and Speed

3 Proposed MLA for High Reliability and Density

4 Conclusion

Outline

1

Introduction

2

Proposed MCC for High Reliability and Speed

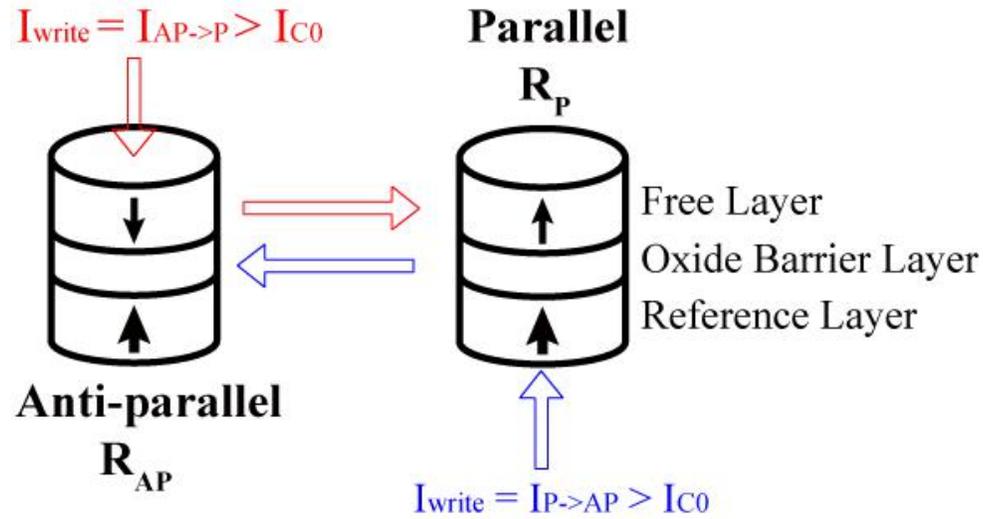
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Proposed MLA for High Reliability and Density

4

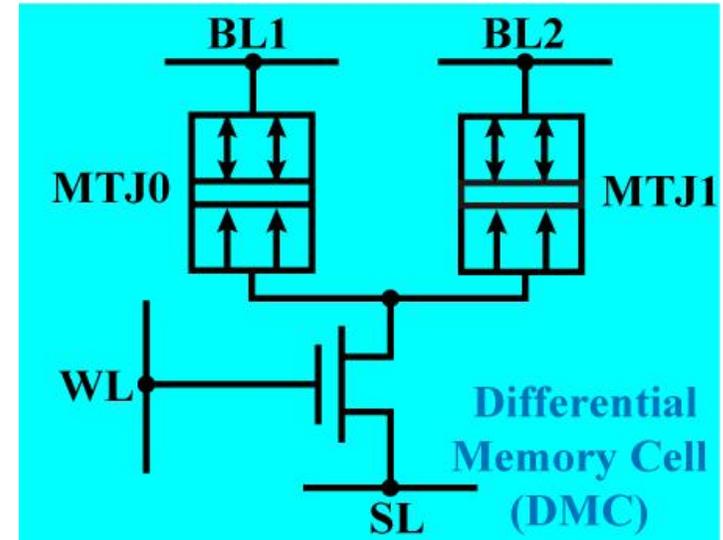
Conclusion

Introduction



$$TMR = (R_{AP} - R_P) / R_P \quad (\sim 100\%, \text{ limited})$$

(a) Structure of MTJ and the STT write mechanism [1]



To improve sensing reliability

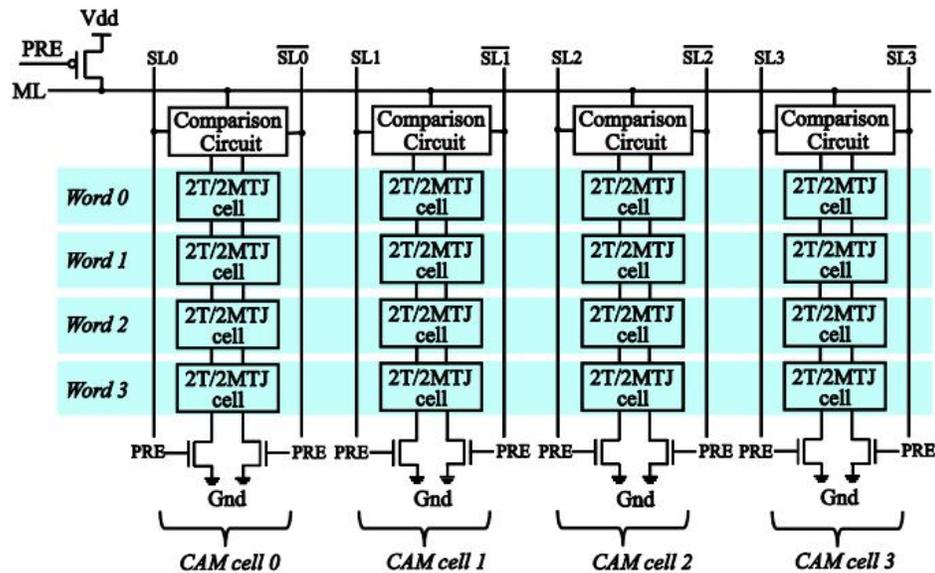
(b) The previously proposed 1T/2MTJ memory cell [2]

[1] M. Wang, W. Cai, D. Zhu, Z. Wang, J. Kan, Z. Zhao, K. Cao, Z. Wang, Y. Zhang, T. Zhang et al., "Field-free switching of a perpendicular magnetic tunnel junction through the interplay of spin-orbit and spin-transfer torques," Nature electronics, vol. 1, no. 11, p. 582, 2018, doi: 10.1038/s41928-018-0160-7.

[2] W. Zhao, L. Torres, Y. Guilleminet, et al. Design of MRAM based logic circuits and its applications[C]//Proceedings of the great lakes symposium on Great lakes symposium on VLSI, 2011: 431-436.

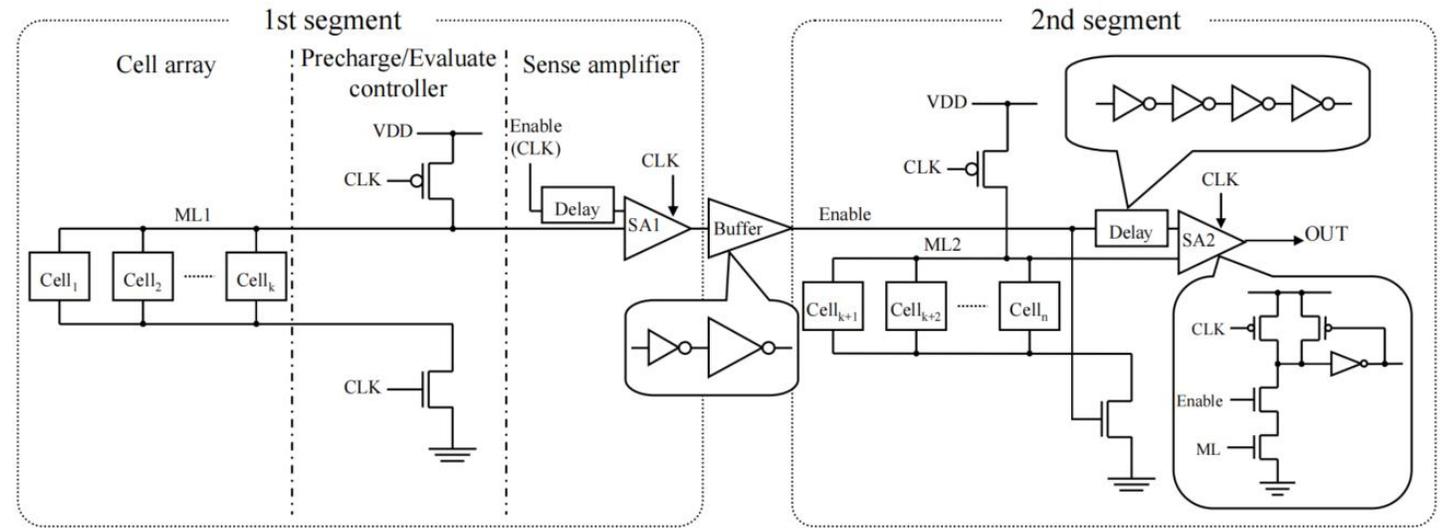
Introduction

Large search delay



(a) Multi-context architecture [5]

Low density and reliability.



(b) Segmented match-line (ML) architecture [6]

[6] S. Matsunaga, A. Katsumata, M. Natsui and T. Hanyu, "Design of a Low-Energy Nonvolatile Fully-Parallel Ternary CAM Using a Two-Level Segmented Match-Line Scheme," 2011 41st IEEE International Symposium on Multiple-Valued Logic, pp. 99-104, 2011, doi: 10.1109/ISMVL.2011.41.

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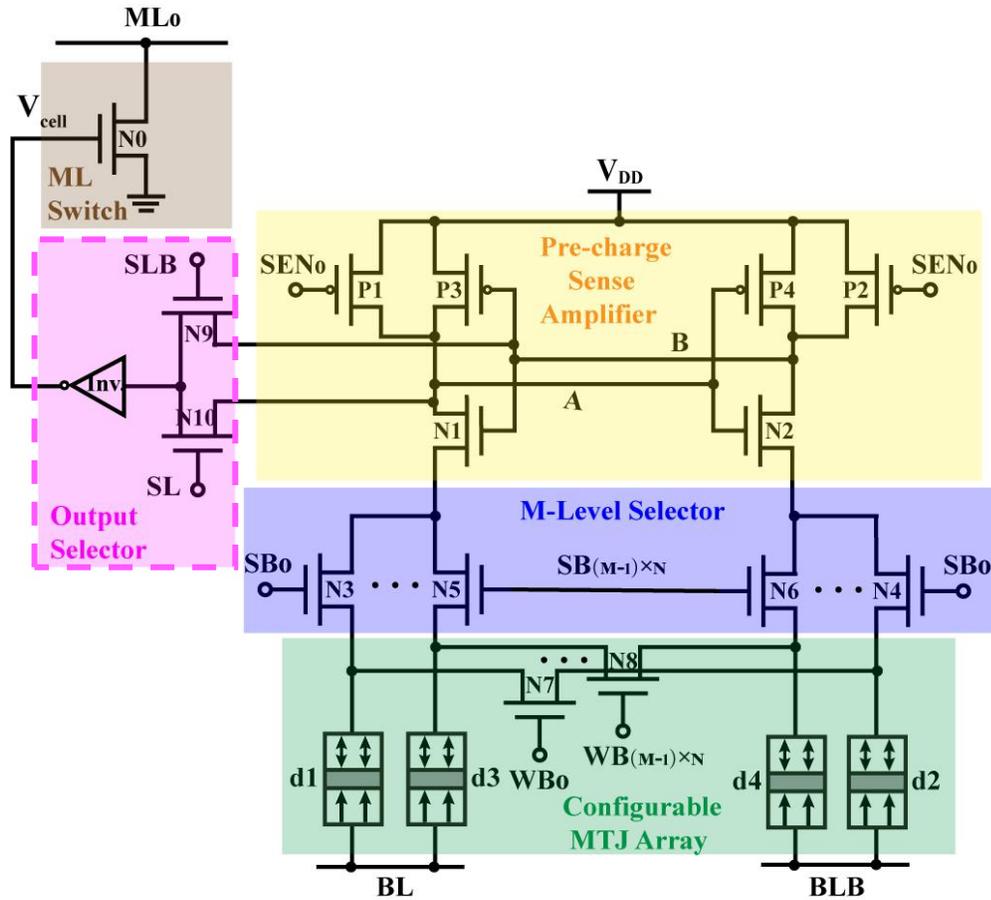
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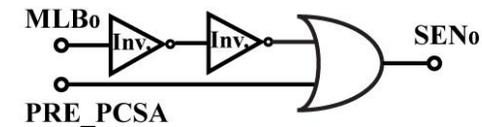
Proposed multi-context cell (MCC)



(a)

➤ Explanation:

1. M denotes the amount of levels in the MLA;
2. N denotes the amount of bits per level in the MLA;
3. i denotes the number of bit in a word;
4. j denotes the number of word in a NV-CAM.

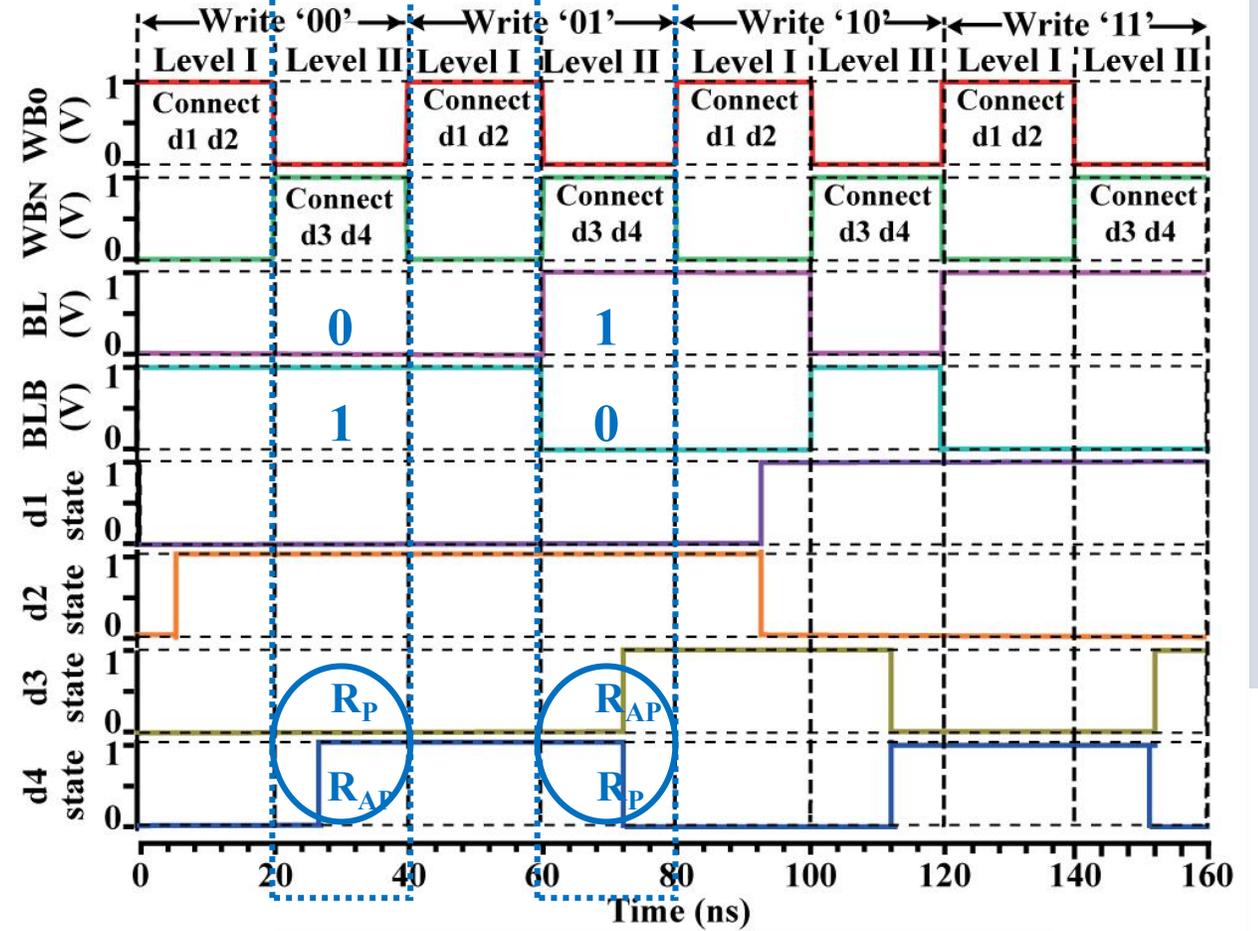
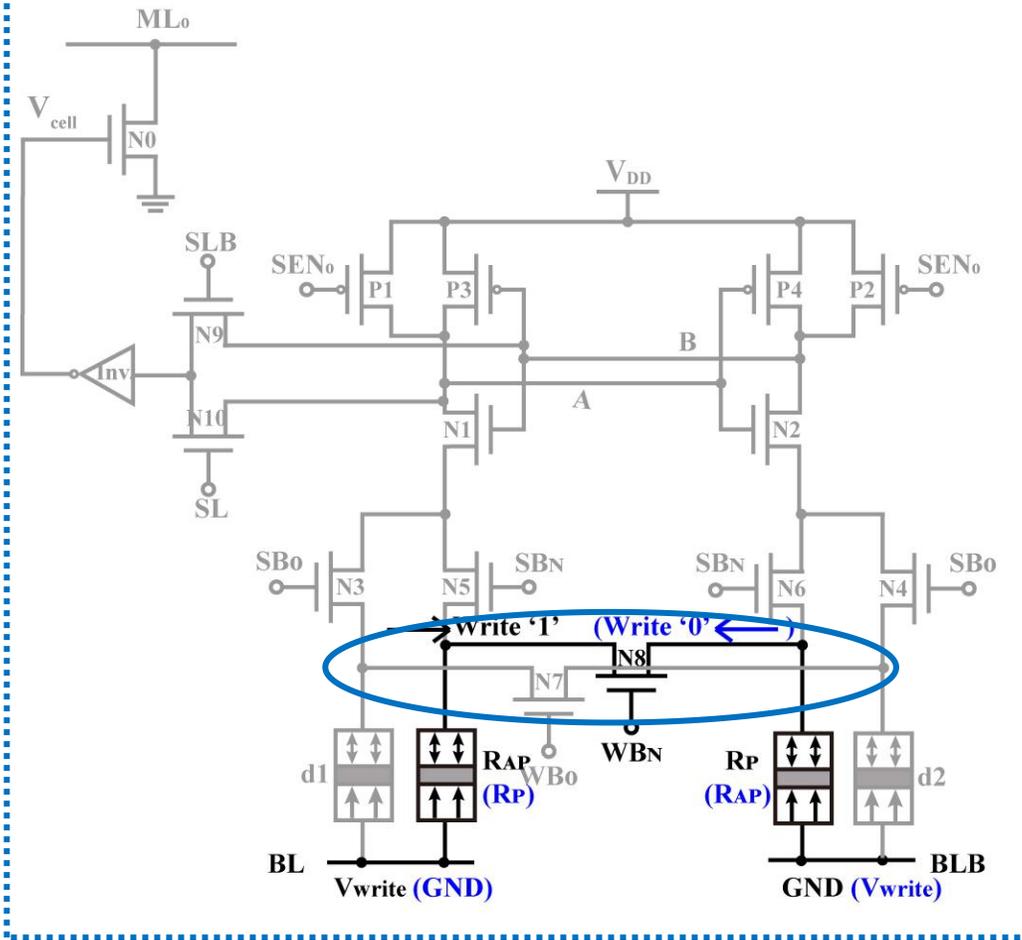


(b)

Schematic of the proposed multi-context cell (MCC) circuit and (b) the SEN generator circuit

The write operation

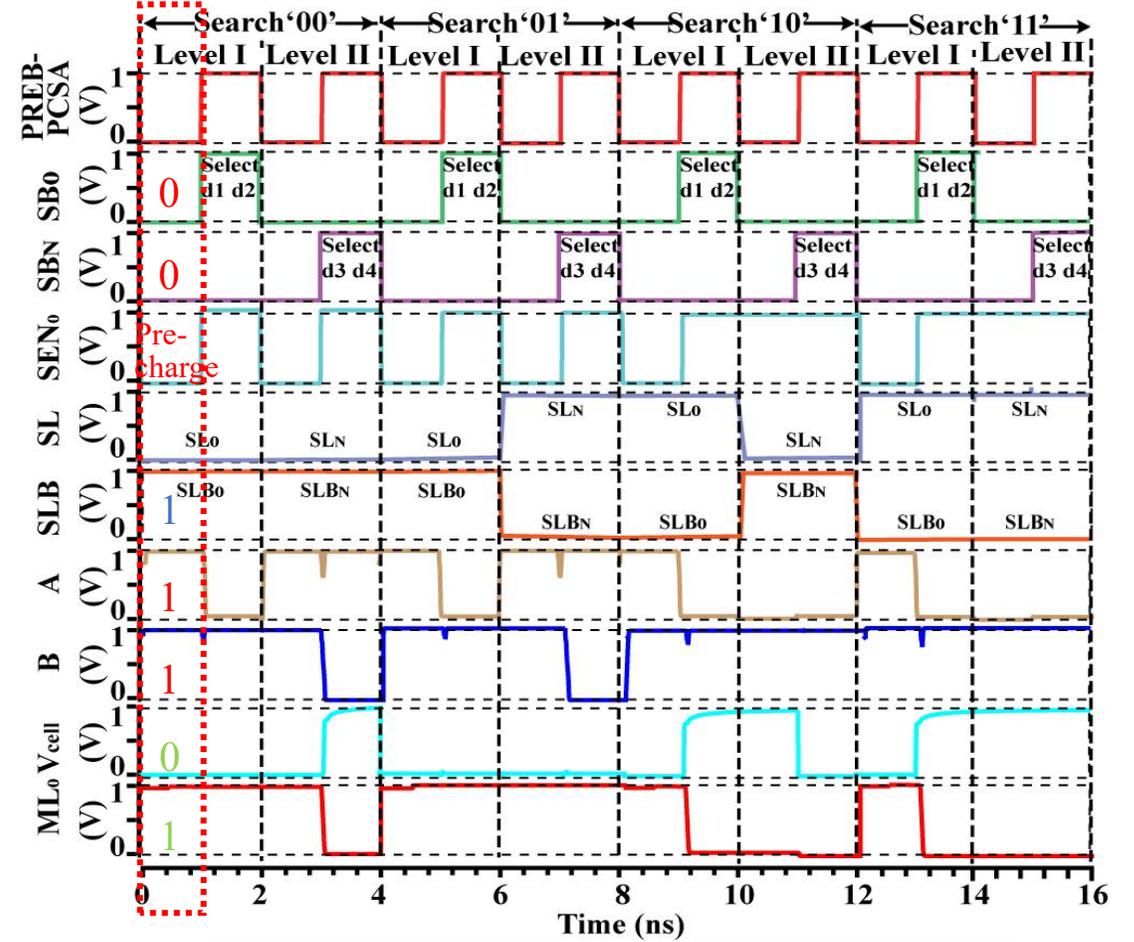
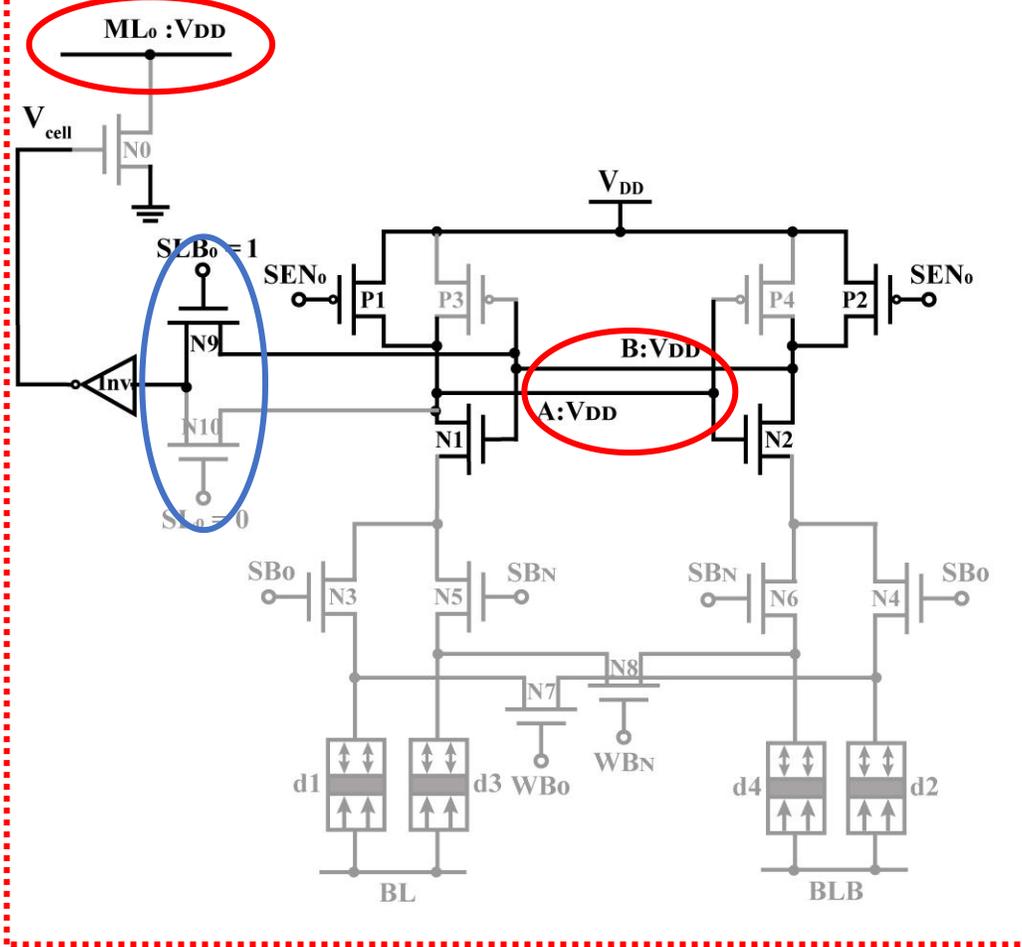
➤ Level II:



Timing diagram of the write operation

The search operation

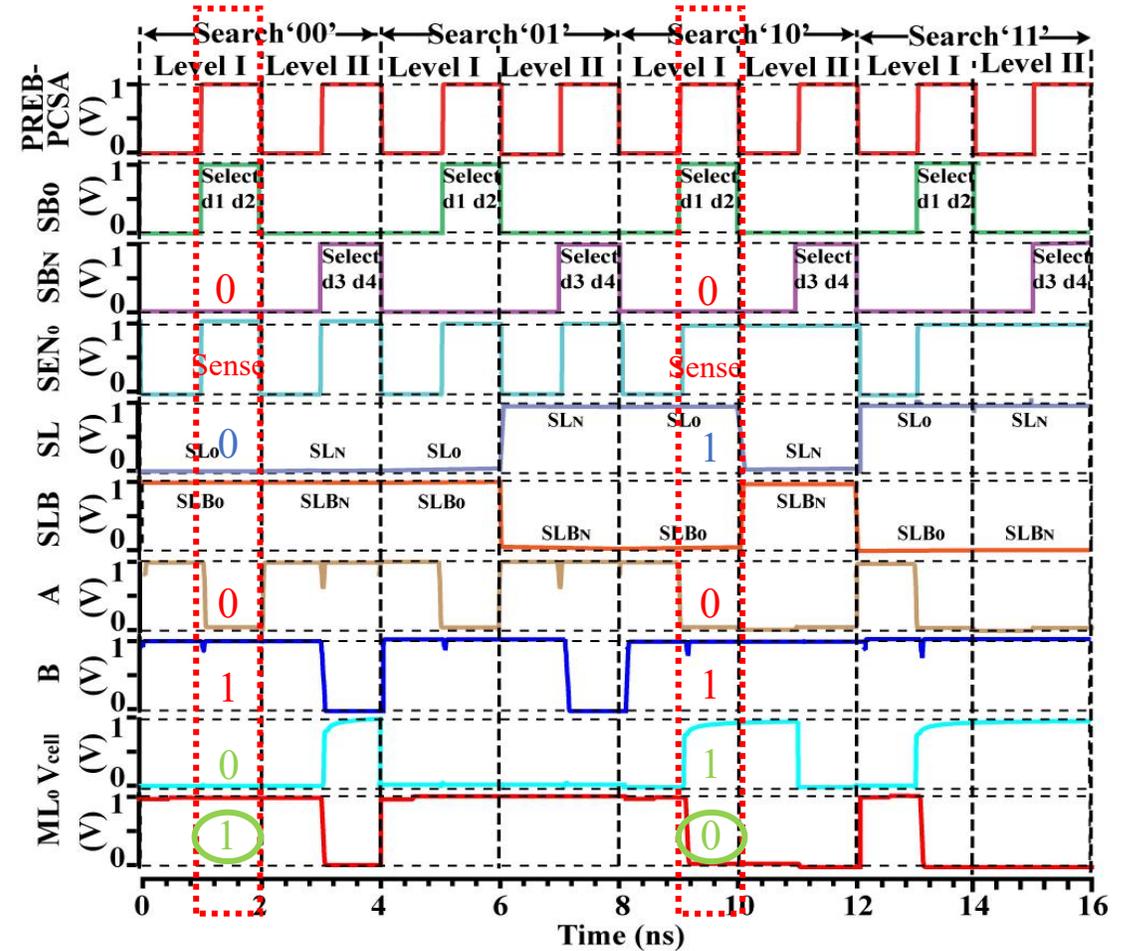
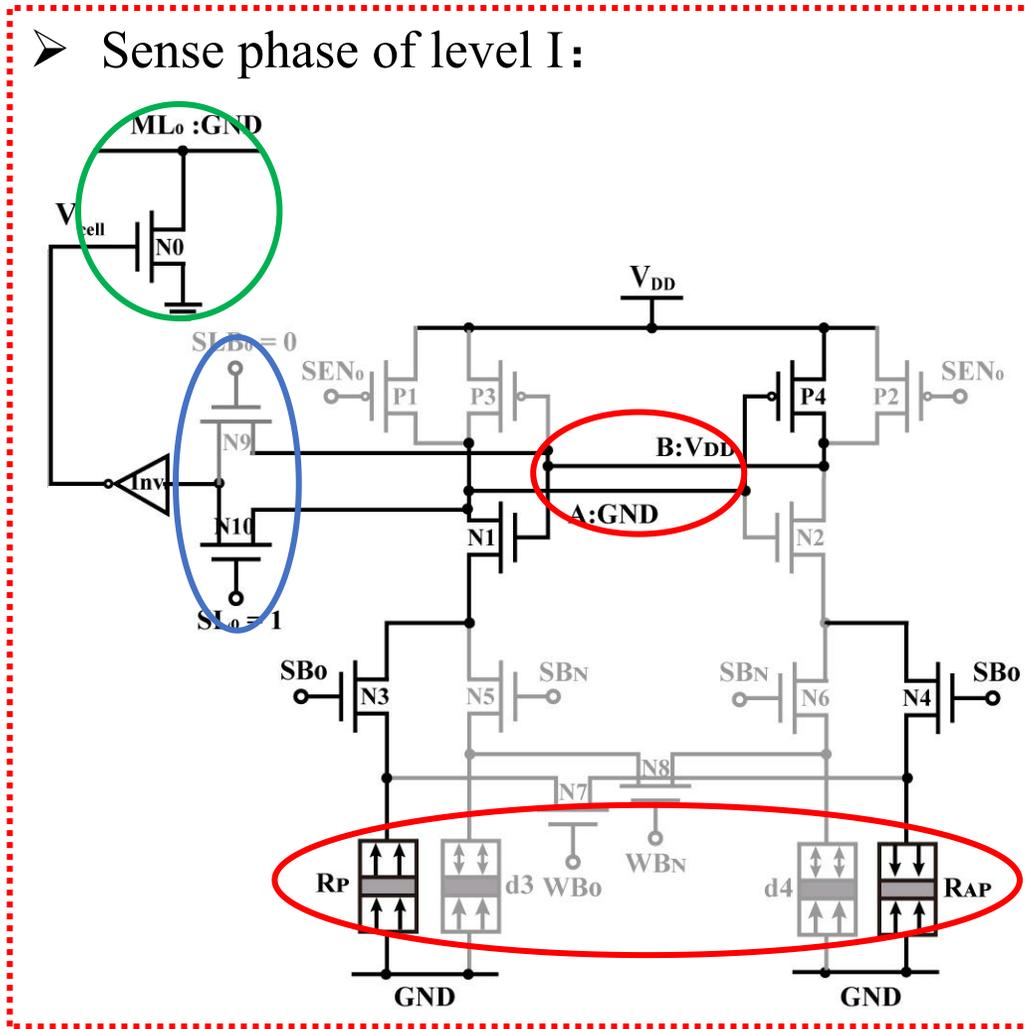
➤ Pre-charge phase of level I:



Timing diagram of the search operation

The search operation

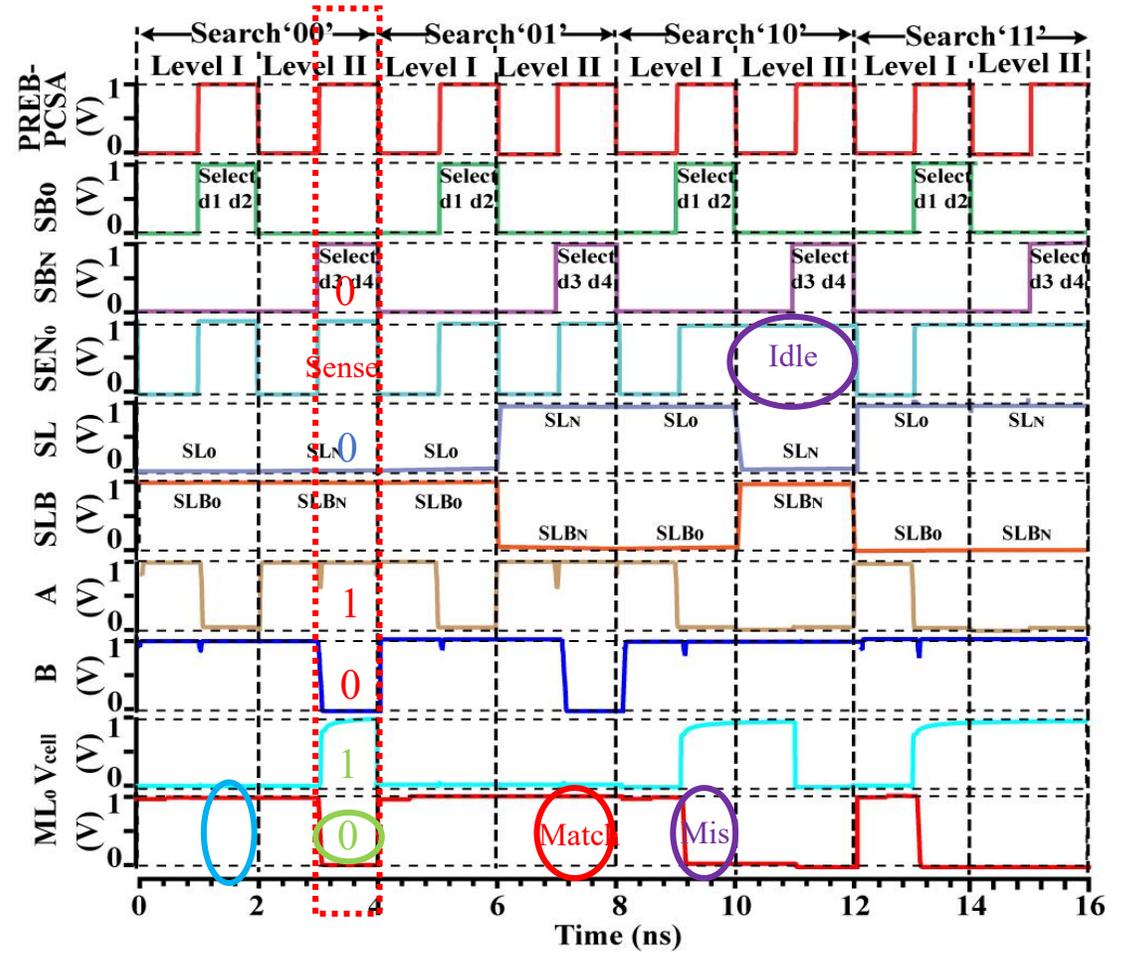
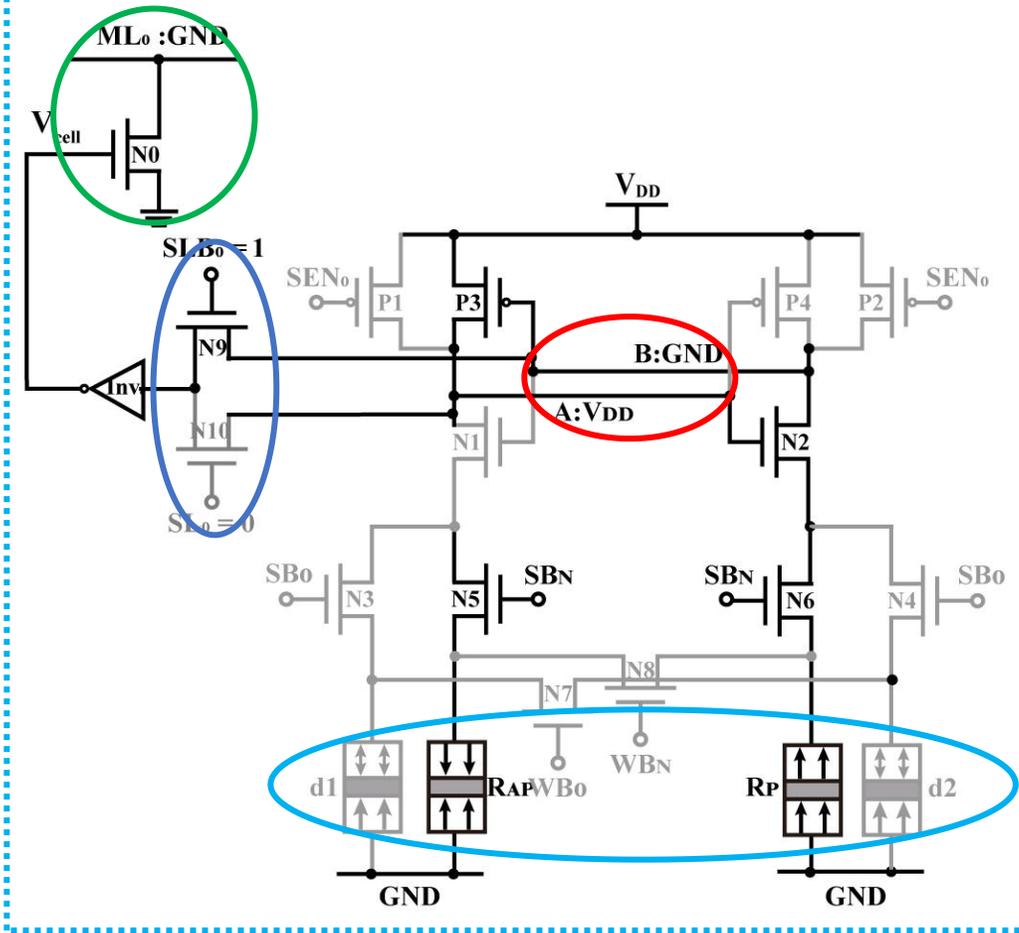
➤ Sense phase of level I:



Timing diagram of the search operation

The search operation

➤ Sense phase of level II:



Timing diagram of the search operation

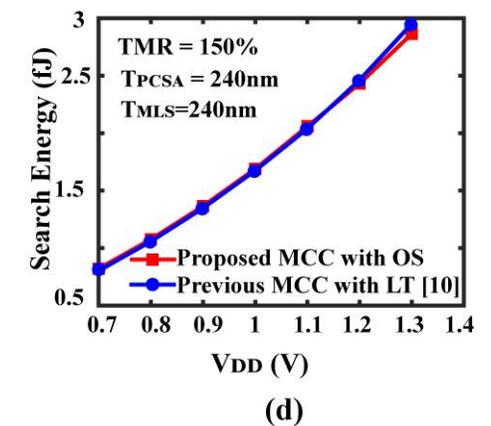
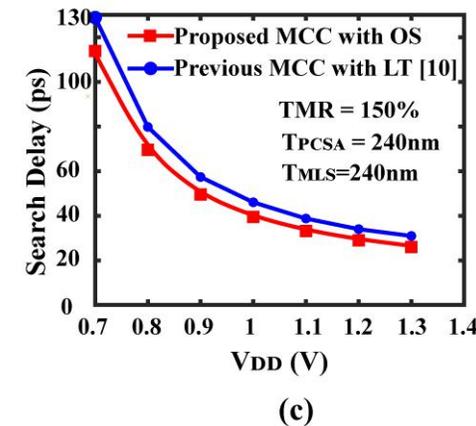
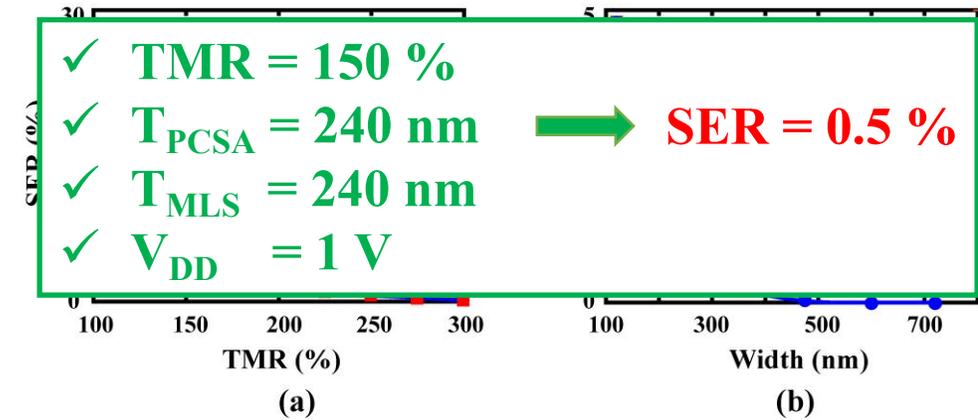
Performance Evaluation

➤ Simulation conditions:

1. A physics-based STT-MTJ compact model [7];
2. A commercial CMOS 40 nm design kit.

CRITICAL PARAMETERS FOR THE PROPOSED NV-CAM

Parameter	Description	Default Value
L	Length of the transistors	40 nm
W	Width of the transistors	120 nm
D	Diameter of MTJ nanopillar	40 nm
TMR(0)	TMR ratio at 0 V_{bias}	1.5
T_{free}	Thickness of free layer	1.3 nm
T_{oxide}	Thickness of oxide layer	0.85 nm
R·A	Resistance-area product	$5 \Omega \cdot \mu\text{m}^2$
ΔTMR	Variation of TMR ratio	0.03
ΔT_{free}	Variation of free layer thickness	0.03
ΔT_{oxide}	Variation of oxide layer thickness	0.03
a	Length of MTJ	40 nm
b	Width of MTJ	40 nm
V_{DD}	Voltage supply	1 V



Performance graph of the proposed and previous scheme

[7] Y. Wang, Hao Cai, Lirida Alves de Barros Naviner, Yue Zhang et al., "Compact Model of Dielectric Breakdown in Spin-Transfer Torque Magnetic Tunnel Junction," in IEEE Transactions on Electron Devices, vol. 63, no. 4, pp. 1762-1767, April 2016, doi: 10.1109/TED.2016.2533438.

Outline

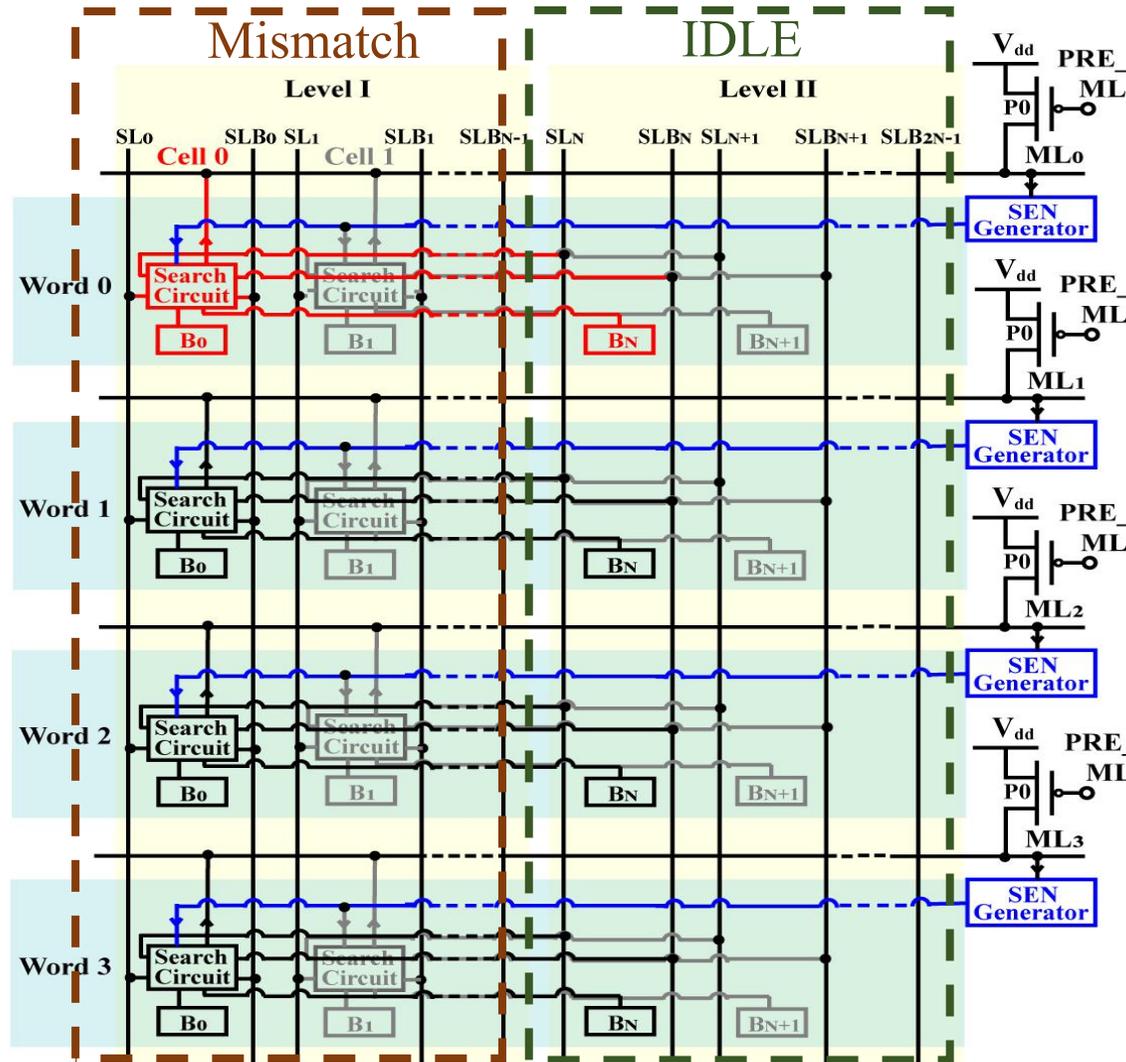
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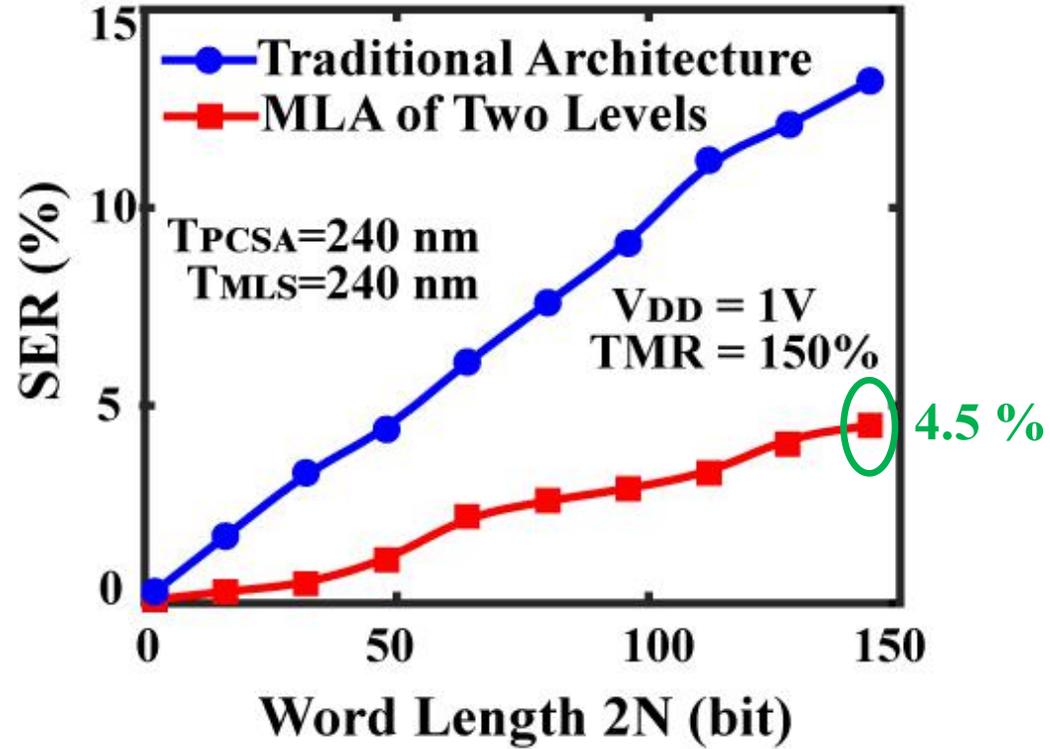
Proposed multi-level architecture (MLA)



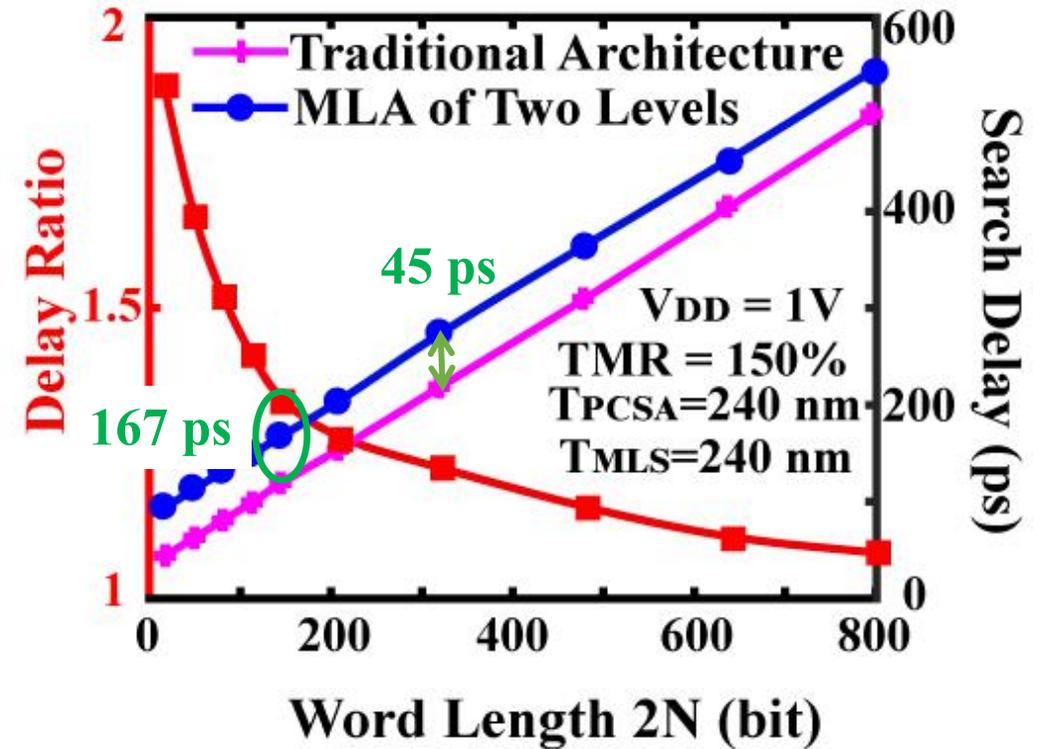
- ✓ Two levels
- ✓ Level I is matched, level II is performed
- ✓ Level I is mismatched, level II is idle

Schematic of a $4 \times 2N$ NV-CAM in the proposed multi-level architecture (MLA)

Performance Evaluation

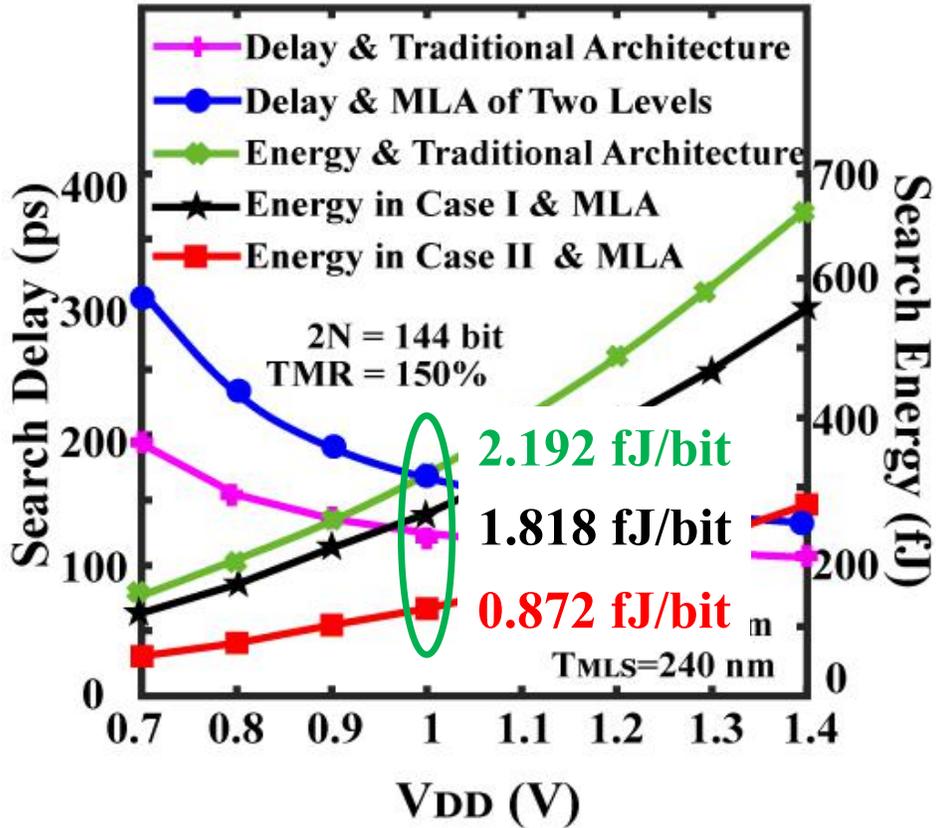


(a) SER with different word length



(b) Search delay and ratio with different word length

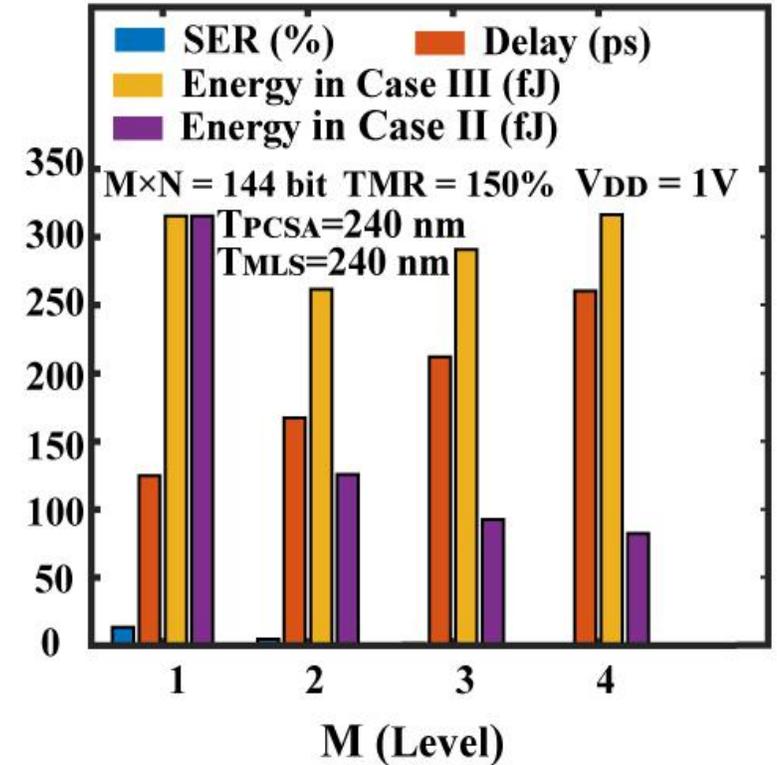
Performance Evaluation



(c) Search delay and energy with different V_{DD}

➤ Amount of transistors per bit: $11/M+3$

- ✓ Case I:
1-bit mismatch in level II
- ✓ Case II:
1-bit mismatch in level I
- ✓ Case III:
Both levels match



(d) Performance of a 1×144 NV-CAM with different M

Outline

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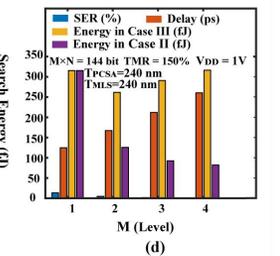
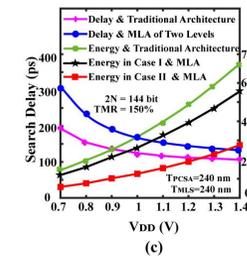
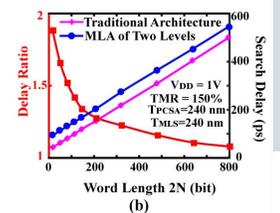
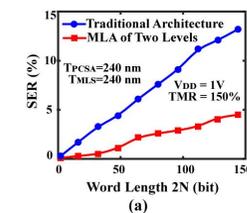
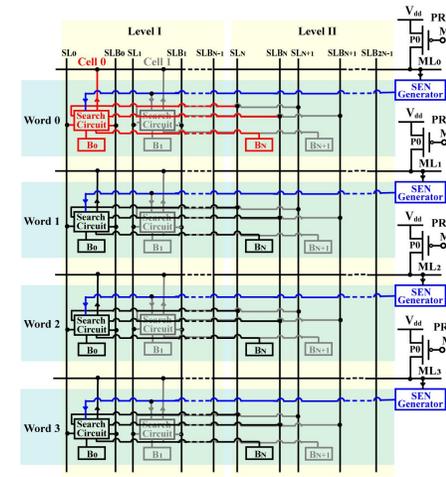
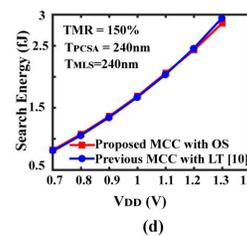
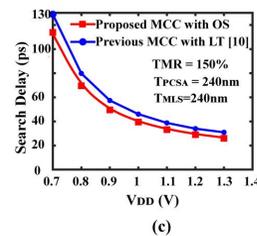
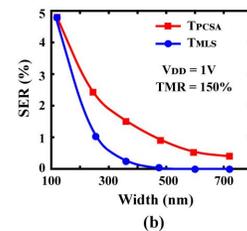
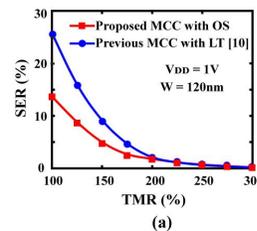
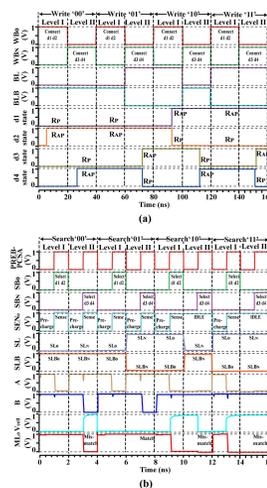
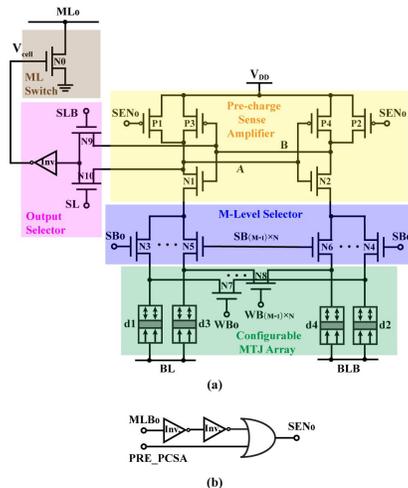
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Conclusion

- A **multi-context cell (MCC)** circuit by employing an **output selector (OS)** instead of a logic tree (LT)
 - Improve the **reliability** and **bit search speed** by reducing transistors' amount in discharge branches.
 - Improve the **area efficiency** by integrating multiple DMCs in one NV-CAM cell.
 - TMR, T_{PCSA} , T_{MLS} and V_{DD} are set to be **150 %**, **240 nm**, **240 nm** and **1 V**, respectively.
- A **SEN generator** to realize the **multi-level architecture (MLA)** for NV-CAM
 - Improve the **reliability** and **word search energy** by bringing inessential search operations to idle state.
 - The cost of search delay is little.
 - Improve the performance of NV-CAM by increasing levels' amount.



Thanks for your attention

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